

40. (Once Amended) A process for the contacting of a wire conductor in the course of the manufacture of a transponder unit arranged on a coil substrate and including a wire coil with wire windings for forming a wire coil on a surface plane of the substrate and a chip unit having a terminal area, the process comprising the steps of:

in a first phase [in which the] guiding the wire conductor [is guided] away via a terminal area or a region accepting the terminal area and is fixed on the substrate relative to the terminal area or the region assigned to the terminal area; and

in a second phase [in which the] effecting a connection of the wire conductor to the terminal area [is effected] with a connecting instrument and a wire conductor is connected extending in parallel to the surface plane of the windings of the wire coil.

Please amend claim 56 as follows:

56. (Once Amended) The process according to claim 40, further comprising a preparatory treatment of [the] an aluminum surface of the terminal area prior to the connection of the wire conductor to the terminal area.

Please amend claim 57 as follows:

57. (Once Amended) The process according to claim 56, wherein with a view to the preparatory treatment a mechanical elimination of of an oxide layer disposed on the aluminum surface is effected by subjecting the terminal area to the action of an ultrasonic instrument.